Information Notice
Reference: W2568660434 Metal/Backend Evaporation system

Introduction

- This Information Notice forms part of the European open Tender procedure for a Metal/Backend Evaporation system published on 03-12-2025 under TNO reference number W2568660434.
- This Information Notice provides a record of the questions submitted by the Tenderers up to and including the date of publishment of this Informaton Notice, with the answers provided by TNO.
- If Tenderers have asked questions of similar nature, all such questions have nevertheless been included in this Information Notice and answered separately. This may result in repetition of information.
- Where a company name was mentioned in a question, it has been replaced by another word or term to anonymize the questions.
- TNO advises you to read the entire Information Notice.
- All information in the Information Notice is classified as Confidential and may only be used for the purpose of submitting a Tender for this procurement.
-The Information Notice has been made available on TenderNed through publication at www.tenderned.nl and added as a document.

The Information Notice serves to provide any additions/changes to the Tender Documents and to communicate announcements from TNO.

Where further clarification of the requirements is provided, this must be taken into account when answering Annex A04 at the time of when compiling the tender. If, for example an alternative is accepted in the Information Notice, Annex A04 will not be revised. The tenderer can answer the question for compliancy with "yes" in both cases (compliancy to the original requirement or compliancy to the alternative). In case a requirement no longer applies, leave the check box in Annex A04 on " select".

Nr	Subject	Question	Answer
1	Annex C02	Would it be acceptable to change the payment terms to: 30% at PO/50% at delivery/20% after final acceptance (including test period)? This better aligns payment with delivery and transfer of risk, while still retaining a portion of the payment until final acceptance.	This payment schedule is acceptable for TNO. Together with this information notice, a new version of the following documents are published: Annex C02 and Annex A04. The Tenderer to whom the Contract will be awarded must provide a bank guarantee to TNO, covering at least 30% of the total price. The Bank guarantee and the bank who issues the Bank guarantee have to be approved by TNO (minimal A rating). TNO must have the right to draw the bank guarantee in any and all cases where Tenderer falls short in fulfilling its obligations under the Contract. The validity of the bank guarantee may not expire until approval of the SAT by TNO Management and Procurement.
2	Annex A04	In items R-1200-025/030/035, the thickness uniformity is defined as (max-min)/((max+min)/2), resulting in a ± value (e.g. ±3%). We assume this is not a ± value. Standard practice, thickness uniformity is calculated as either (max-min)/(max+min) or equivalently (max-min)/(2*avg), which yields a ± value. We request confirmation/clarification on definition of thickness uniformity.	This is correct. It should be 3% of the average (max-min)/((max+min)/2)
3	Proc. Guide 5.2.2	Core Competence 1 We have fulfilled a fully automated e-beam evaporator system used for 6'' wafers at an industrial production scale <3years However contract value was lower due to limited budget of this tender. For a other large coater budget > 600kEUR however is a sputter system for industrial customer but is none ebeam. Can we combine these references as our trackrecord is proven here.	Please provide both references and TNO will combine them in the evaluation.
4	Proc. Guide 5.2.2	Core Competence 2 We have build a robot handling system for 6inch InP and are currently testing wafer take-overs of 4inch and 6inch InP wafers in our lab to meet 10.000 passes. However this is an internal test setup as we see the Indium phosphide wafer take-over as one of the critical items in the project.	TNO agrees with your view.

5	Annex A04	R-1000-010 As this is a backend process what is expected deformation and stress of the InP wafer. As we know that InP in backend can be highly stressed and brittle for wafer handling/take-over. What deformation / stress is expected here.	TNO expects not more than 15 µm of bow or warp deformation on the wafers.
6	Annex A04	R-2200-025 ISO5: will the equipment be placed in grey room with entrance door/cassette towards ISO5 or will the full system be placed inside ISO5 ?	In the current design the entire system is in the cleanroom.
7	Annex A04	Are there restrictions in regards handling InP wafer and (larger)contact areas for flip and rotate and handler (e.g. use of lift pins/fork/edge grip)	The wafers should not be damaged by the handling system. See also chip-out requirement R-2100-010. The wafer holding or clamping system should not cause significant edge shadowing or surface scratching. Ideally < 2 mm but certainly not more than 5 mm